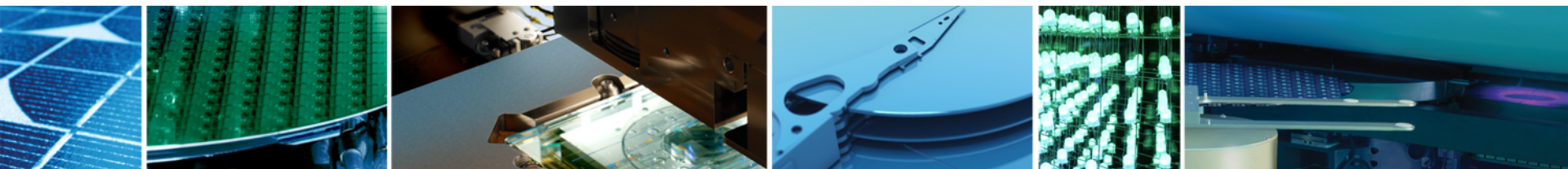




Automated Yield Management Solution for LED Manufacturing

DOE Agreement# DE-EE0003159

June 13, 2012



DOE Project Objectives & Scope

- Objective

- Develop a comprehensive yield management system to enable automated process control in LED manufacturing

- Key Tasks

- Extend detection sensitivity of yield-limiting defects for substrate and epi inspection platform
- Accelerate root cause analysis in wafer fab process with comprehensive yield management solutions (YMS) analysis

- Team

- KLA-Tencor – development of inspection HW and YMS SW platforms
- Philips Lumileds – test samples and beta validation

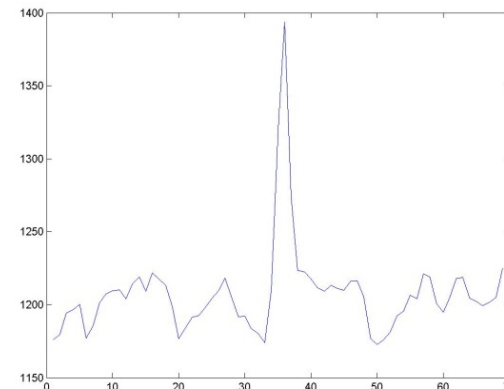
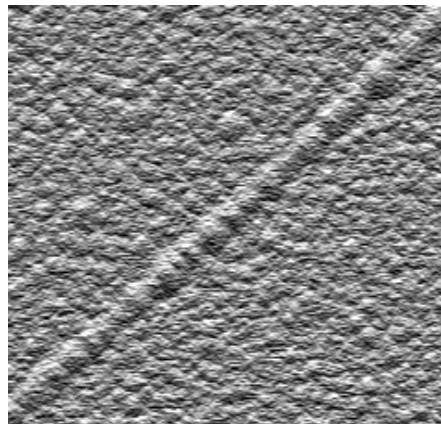
Project Scope - Hardware

Develop high sensitivity Candela inspection platform

Extend detection capability to critical yield-relevant and reliability defects

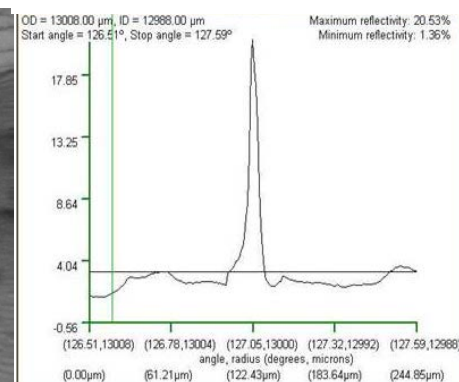
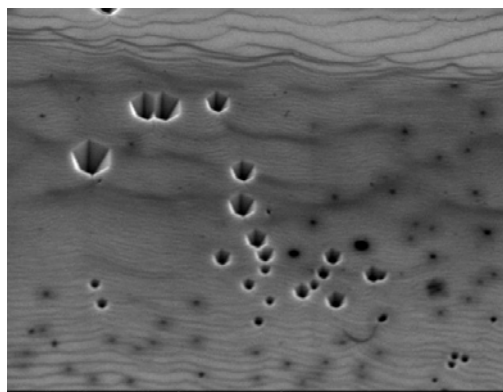
Improved detection of micro-scratches and cracks

Substrate micro-scratches/ micro-cracks are known reliability defects that result in premature field failure



Improved detection of killer epi defects in sub-micron regime

Increase sensitivity and separation from nuisance particles

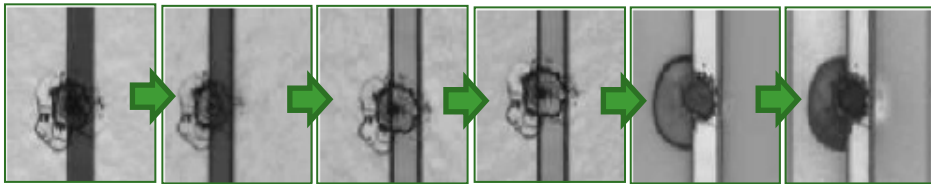
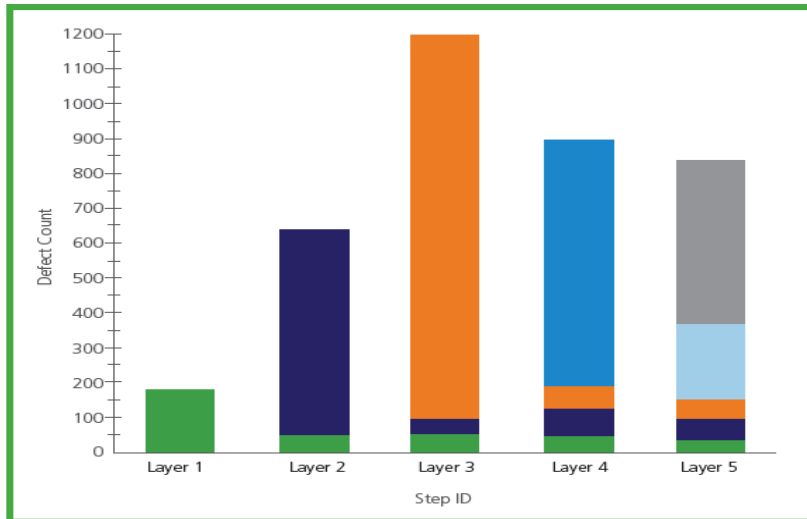


Project scope – Software

Correlation of inspection results in LED manufacturing

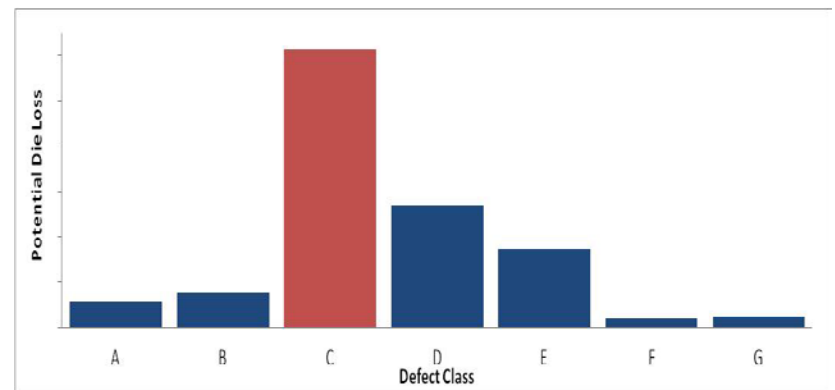
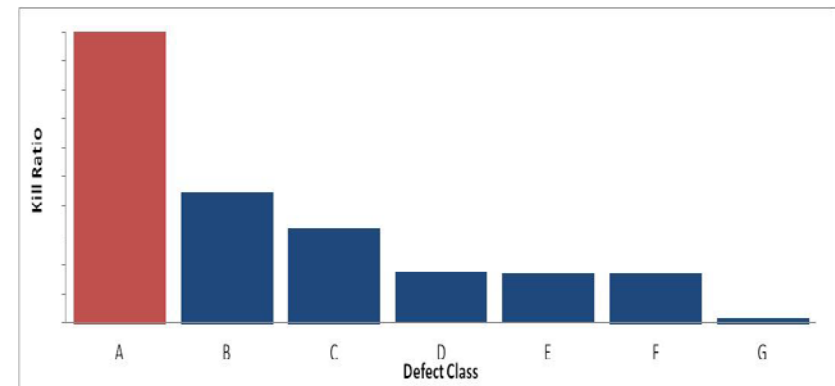
Defect Source Analysis (DSA)

Step contribution and defect transition



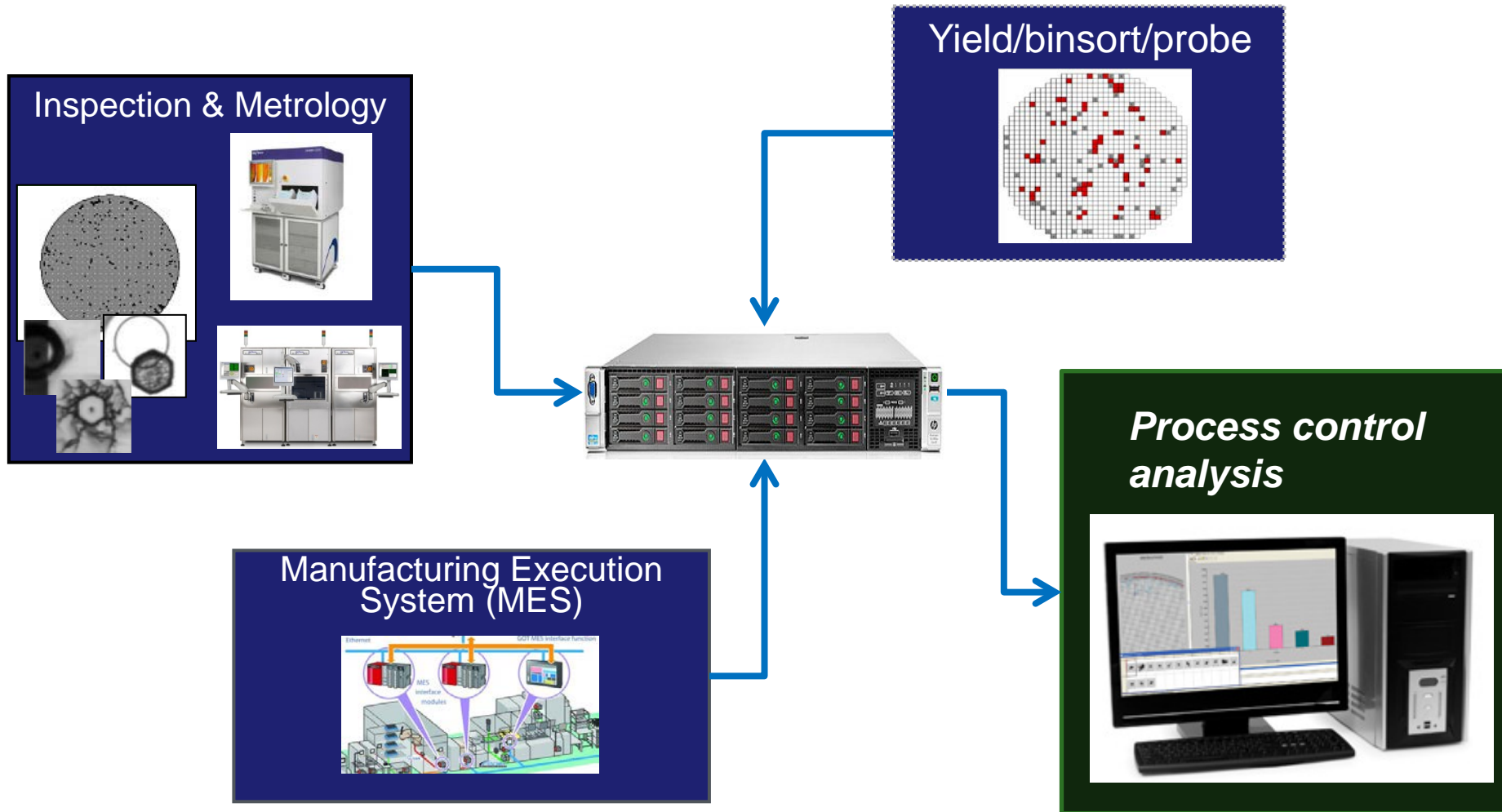
Yield Contribution to Defectivity

Kill ratio and potential die loss



KLARITY LED © Software Development

Tool connectivity and yield management platform



Key Milestones Progress:

HW: Candela 8620, SW: Klarity-LED Development

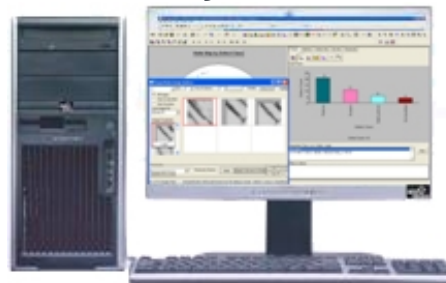
Year 1 Progress

- ✓ Development of Candela hardware
- ✓ Initial validation of increased sensitivity and classification
- ✓ Field testing
- ✓ Development of YMS engine and platform for tool connectivity
- ✓ Validation of DSA, SPC, and other functionality
- ✓ Field testing

Candela 8620



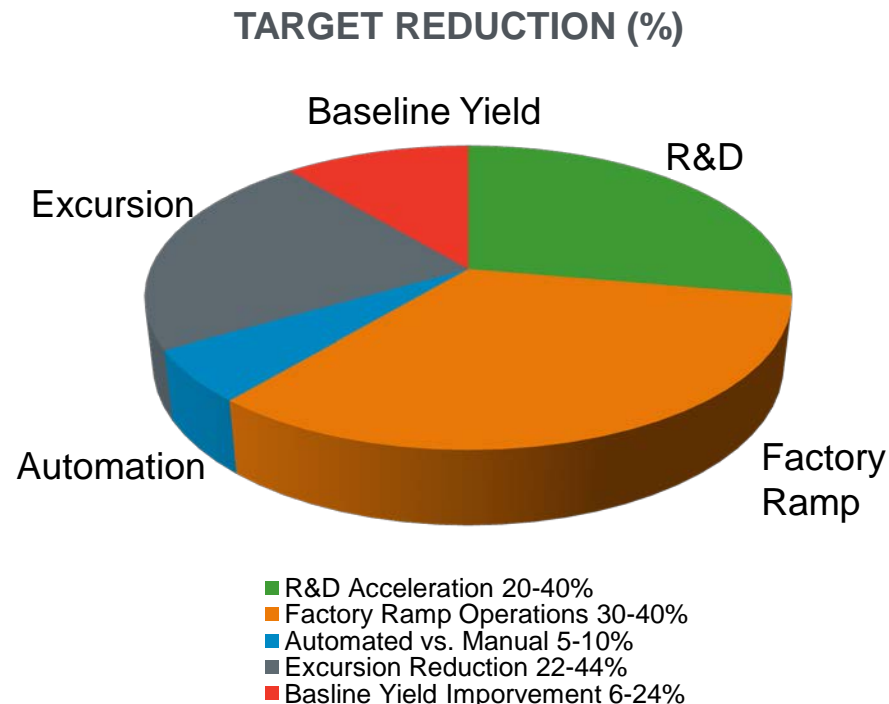
Klarity-LED YMS



Year 2 Objectives

- ✓ Field validation across multiple material systems
- ✓ Development of recipe algorithms
- ✓ Production robustness
- ✓ Field validation of tool connectivity
- ✓ Incorporate parametric yield information into analysis engine
- ✓ Production testing of process excursions, root cause and SPC

LED Manufacturing Cost Reduction from Improved Process Control



Summary

- DOE program on integrated automated yield management on track to complete by June '12
 - **Yield improvement value realized** => Best known inspection methods implemented with Candela 8620 at sapphire suppliers and LED device fabs
 - **Faster root-cause & excursion detection value realized** => Increasing transition from manual operators -> inline automated inspection; implementation of Klarity LED YMS in LED manufacturing environment

Candela 8620 Industry Recognition

